

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field device integration (FDI) –
Part 101-1: Profiles – Foundation Fieldbus H1**

**Intégration des appareils de terrain (FDI) –
Partie 101-1: Profils – Foundation Fieldbus H1**



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FIELD DEVICE INTEGRATION (FDI) –

Part 101-1: Profiles – Foundation Fieldbus H1

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International Standard IEC 62769-101-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) support for Package developers to build EDDs targeted for today's EDD bases system under a single development tool.

The text of this International Standard is based on the following documents:

CDV	Report on voting
65E/620/CDV	65E/683/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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FIELD DEVICE INTEGRATION (FDI) –

Part 101-1: Profiles – Foundation Fieldbus H1

1 Scope

This part of IEC 62769 specifies the IEC 62769 profile for IEC 61784-1_CP 1/1 (FOUNDATION™ Fieldbus H1)¹.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-5-9:2014, *Industrial communication networks – Fieldbus specifications – Part 5-9: Application layer service definition – Type 9 elements*

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus Profiles*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC/IEEE 8802-3*

IEC 61784-3:2016, *Industrial communication networks – Profiles – Part 3: Functional safety fieldbuses – General rules and profile definitions*

IEC 61804 (all parts), *Function blocks (FB) for process control and electronic device description language (EDDL)*

IEC 62541-6, *OPC unified architecture – Part 6: Mappings*

IEC 62541-100:2015, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-1, *Field device integration (FDI) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

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